

**Amendments to the Specification**

- 1) Please insert the following paragraph at page 1, line 3:

This application is a 371 of International PCT Application PCT/IB2005/000522, filed February 24, 2005.
- 2) Please replace the subtitle at page 1, below the above paragraph, with the following:

**Background [[:]]**
- 3) Please replace the paragraph at page 3, line 19, with the following:

It is disclosed, e.g. in Jpn. J. Appl. Phys., Vol. 42, No. 6A, pp. L578-L580, June 2003, Applied Physics Letters, Vol. 80, No. 13, pp. 2362-2364, April 2002, United States Published Applications 2003/0111678, 2003/0207549, 2003/0207549 or U.S. Patent No. 06399208, Japanese patent application published as 2000272283, various processes to make dielectric films. However, all of these films suffer from one or more of the disadvantages discussed below.
- 4) Please replace the subtitle at page 5, line 28, with the following:

**Summary of the invention-:**
- 5) Please insert the following paragraph at page 24, line 16:

It will be understood that many additional changes in the details, materials, steps and arrangement of parts, which have been herein described in order to explain the nature of the invention, may be made by those skilled in the art within the principle and scope of the invention as expressed in the appended claims. Thus, the present invention is not intended to be limited to the specific embodiments in the examples given above.

Appl. No. 10/591,629  
Attorney Docket No. Serie 6550 CIP  
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- 6) Please replace the subtitle at page 25, line 1, with the following text:

**CLAIMS** What is claimed is: